



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN #20150313000
Qualification of TI Malaysia as an Alternate Assembly and Test Site for the
MC33063AD
Change Notification / Sample Request

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

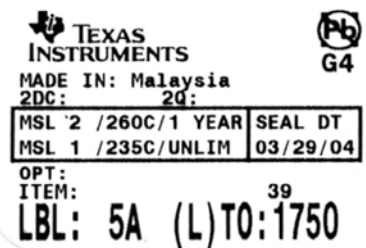
PCN Team
SC Business Services

PCN# 20150313000
Attachment: 1

Products Affected:

According to our records, there are the affected device(s) that you have purchased within the past twenty-four (24) months. Technical details of this Product Change follow on the next page(s).

PCN Number:	20150313000		PCN Date:	3/16/2015										
Title:	Qualification of TI Malaysia as an Alternate Assembly and Test Site for the MC33063AD with BOM differences													
Customer Contact:	PCN Manager		Dept:	Quality Services										
Proposed 1st Ship Date:	06/16/2015		Estimated Sample Availability:	Provided upon Request										
Change Type:														
☒	Assembly Site	☐	Assembly Process	☒	Assembly Materials									
☐	Design	☐	Electrical Specification	☐	Mechanical Specification									
☒	Test Site	☐	Packing/Shipping/Labeling	☐	Test Process									
☐	Wafer Bump Site	☐	Wafer Bump Material	☐	Wafer Bump Process									
☐	Wafer Fab Site	☐	Wafer Fab Materials	☐	Wafer Fab Process									
		☐	Part number change											
PCN Details														
Description of Change:														
Texas Instruments is pleased to announce the qualification of TI Malaysia as an alternate Assembly and test site for the MC33063AD. Differences between devices built between the 2 locations is shown below: <table border="1" style="margin-left: auto; margin-right: auto;"> <thead> <tr> <th></th> <th>TI Mexico</th> <th>TI Malaysia</th> </tr> </thead> <tbody> <tr> <td>Mount Compound</td> <td>4147858</td> <td>4042500</td> </tr> <tr> <td>Location (City)</td> <td>Aguascalientes</td> <td>Kuala Lumpur</td> </tr> </tbody> </table> Test coverage, insertions, conditions will remain consistent with current testing and verified with test MQ.							TI Mexico	TI Malaysia	Mount Compound	4147858	4042500	Location (City)	Aguascalientes	Kuala Lumpur
	TI Mexico	TI Malaysia												
Mount Compound	4147858	4042500												
Location (City)	Aguascalientes	Kuala Lumpur												
Reason for Change:														
Continuity of Supply														
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):														
None														

Changes to product identification resulting from this PCN:		
Assembly Site		
TI Mexico	Assembly Site Origin (22L)	ASO: MEX
TI Malaysia	Assembly Site Origin (22L)	ASO: MLA
Sample product shipping label (not actual product label)		
  (1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY (1T) 7523483SI2 (P) (2P) REV: (V) 0033317 (20L) CSO: SHE (21L) CCO: USA (22L) ASO: MLA (23L) ACO: MYS		
Topside Device marking: Assembly site code for MEX= M Assembly site code for MLA= K		

Product Affected

MC33063AD

MC33063ADR


TI Information
Selective Disclosure
Qualification Report

MC33063AD & MC33063ADR Offload from FMX to MLA (SLL Multi-Source)

Approved 02/16/2015

Product Attributes

Attributes	Qual Device: MC33063ADR	QBS Process: TL499ACP	QBS Pkg: MAX232DR	QBS Pkg: RC4558DR	QBS Pkg: SN74LV14ADR	QBS Pkg: ULN2003ADR
Assembly Site	MLA (TIM)	SFAB	MLA (TIM)	MLA (TIM)	MLA (TIM)	MLA (TIM)
Package Family	SOIC (6 mil thick)	PDIP	SOIC	SOIC	SOIC	SOIC
Flammability Rating	-		UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0
Wafer Fab Site	SFAB	SFAB	SFAB	SFAB	SFAB	SFAB
Wafer Fab Process	JI-1	JI-BIP	LBC3S	JI1-Lin	EPIC1-S_SLM	JI-SLM

- QBS: Qual By Similarity

- Qual Device MC33063ADR is qualified at LEVEL1-260CG

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: MC33063ADR	QBS Process: TL499ACP	QBS Package: MAX232DR	QBS Package: RC4558DR	QBS Package: SN74LV14ADR	QBS Package: ULN2003ADR
HAST	Biased HAST, 130C/85%RH	96 Hours	-	3/231/0	3/231/0	1/77/0	1/77/0	1/77/0
AC	Autoclave 121C	96 Hours	-		3/231/0	1/77/0	1/77/0	1/77/0
TC	Temperature Cycle, -65/150C	500 Cycles	-		3/231/0	3/231/0	3/231/0	3/231/0
HTSL	High Temp. Storage Bake, 150C	1000 Hours	-		-	3/231/0	3/231/0	-
HTSL	High Temp. Storage Bake, 170C	420 Hours	-		3/231/0	-	-	3/231/0
HTOL	Life Test, 150C	300 Hours	-	3/231/0	3/231/0	1/77/0	1/77/0	1/77/0
ED	Electrical Characterization	Per Datasheet Parameters	-	Pass	Pass	Pass	Pass	Pass
ESD	ESD-HBM	2500V	1/3/0					
ESD	ESD-CDM	1500V	1/3/0					
LU	Latchup	Per JESD78	1/6/0					
WBS	Bond Strength	Wires	-		3/228/0	1/76/0	1/76/0	1/76/0
LI	Lead Pull to Destruction	Leads	-		3/66/0	1/22/0	1/22/0	1/22/0
FLAM	Flammability (IEC 695-2-2)	--	-		3/15/0	1/5/0	1/5/0	-

FLAM	Flammability (UL 94V-0)	--	-		3/15/0	1/5/0	1/5/0	-
FLAM	Flammability (UL-1694)	--	-		3/15/0	1/5/0	1/5/0	-

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com